OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SDAS065B − DECEMBER 1982 − REVISED JANUARY 1995

- **3-State Buffer-Type Inverting Outputs Drive Bus Lines Directly**
- **Bus-Structured Pinout**
- **Buffered Control Inputs**
- **SN74ALS577A Has Synchronous Clear**
- **Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N, NT) and Ceramic (J) 300-mil DIPs, and Ceramic Flat (W) Packages**

description

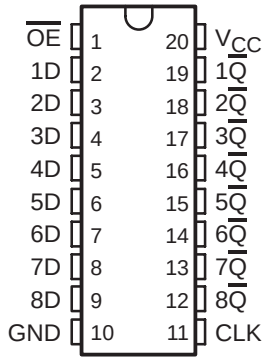
These octal D-type edge-triggered flip-flops feature 3-state outputs designed specifically for bus driving. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These flip-flops enter data on the low-to-high transition of the clock (CLK) input.

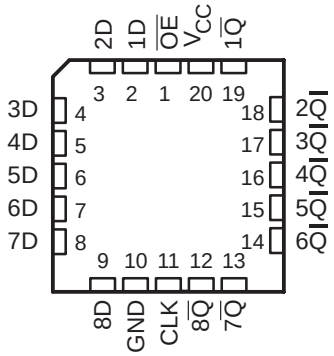
The output-enable ($\overline{OE}$) input does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are disabled.

The SN54ALS576B and SN54AS576 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN74ALS576B, SN74ALS577A, and SN74AS576 are characterized for operation from 0°C to 70°C.

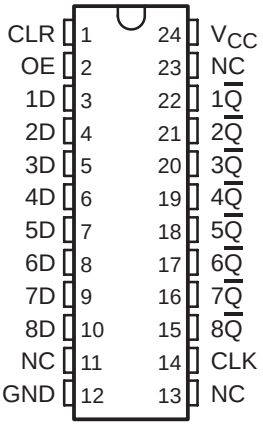
SN54ALS576B, SN54AS576 . . . J OR W PACKAGE
SN74ALS576B, SN74AS576 . . . DW OR N PACKAGE
(TOP VIEW)



SN54ALS576B, SN54AS576 . . . FK PACKAGE
(TOP VIEW)



SN74ALS577A . . . DW OR NT PACKAGE
(TOP VIEW)



NC − No internal connection

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251−1443

Function Tables

′ALS576B, ′AS576 (each flip-flop)

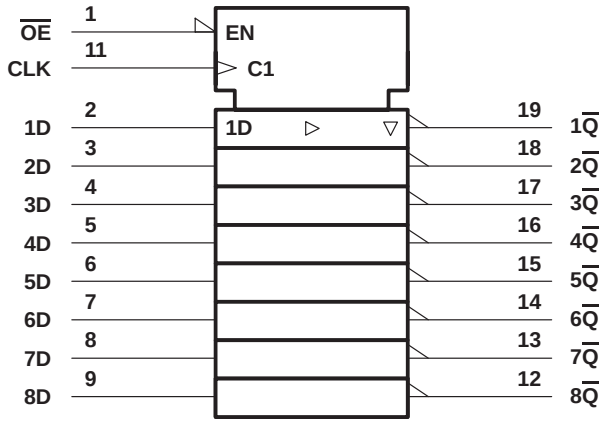
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	$\overline{Q}$
L	↑	H	L
L	↑	L	H
L	L	X	$\overline{Q}_0$
H	X	X	Z

SN74ALS577A (each flip-flop)

INPUTS				OUTPUT
$\overline{OE}$	$\overline{CLR}$	CLK	D	$\overline{Q}$
L	L	↑	X	H
L	H	↑	H	L
L	H	↑	L	H
L	H	L	X	$\overline{Q}_0$
H	X	X	X	Z

logic symbols†

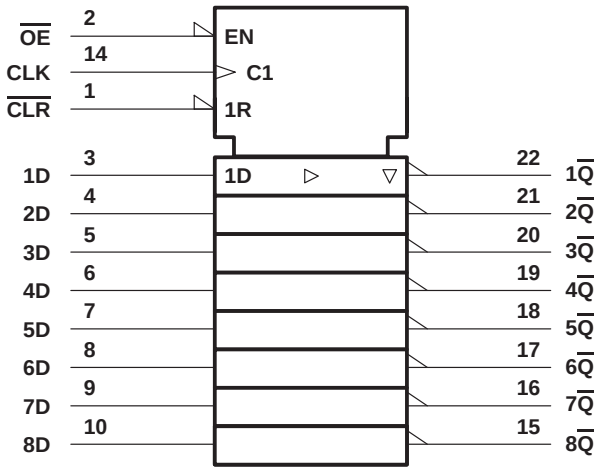
′ALS576B, ′AS576



† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown for the ′ALS576B and ′AS576 are for the DW, J, N, and W packages.

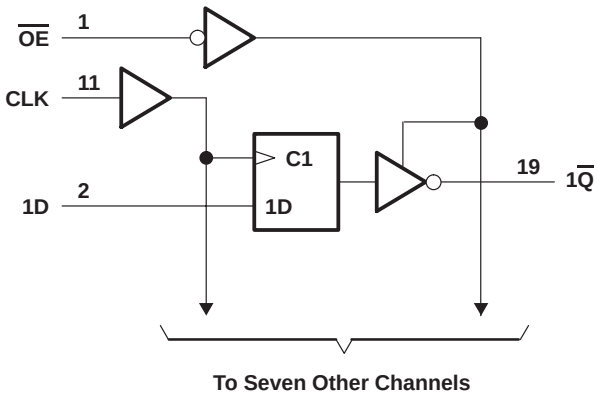
SN74ALS577A



Pin numbers shown for the SN74ALS577A are for the DW and NT packages.

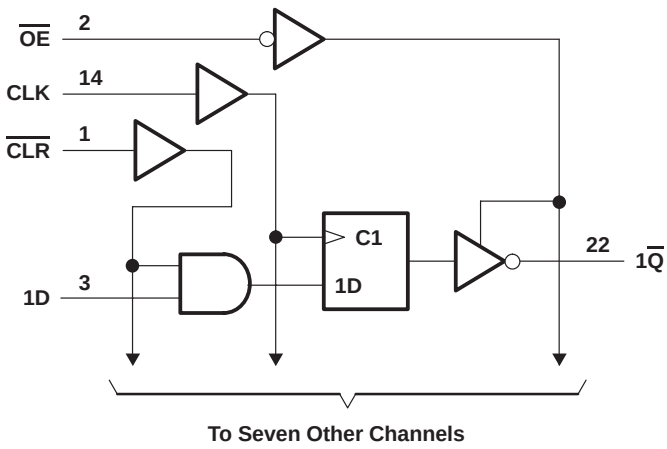
logic diagrams (positive logic)

′ALS576B, ′AS576



Pin numbers shown are for the DW, J, N, and W packages.

SN74ALS577A



Pin numbers shown are for the DW and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 7 V
Voltage applied to a disabled 3-state output . . . . . 5.5 V
Operating free-air temperature range, T_A: SN54ALS576B . . . . . −55°C to 125°C
SN74ALS576B, SN74ALS577A . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54ALS576B			SN74ALS576B SN74ALS577A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current				−1			−2.6	mA
I_{OL}	Low-level output current				12			24	mA
f_{clock}	Clock frequency	′ALS576B	0		22	0		30	MHz
		SN74ALS577A				0		30	
t_w	Pulse duration	′ALS576B, CLK high or low	25			16.5			ns
		SN74ALS577A, CLK high or low				16.5			
t_{su}	Setup time before CLK↑	Data	15			15			ns
		SN74ALS577A $\overline{CLR}$				15			
t_h	Hold time after CLK↑	Data	4			0			ns
		SN74ALS577A $\overline{CLR}$				0			
T_A	Operating free-air temperature		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS576B			SN74ALS576B SN74ALS577A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −0.4 mA	V_{CC} −2			V_{CC} −2			V
	V_{CC} = 4.5 V	I_{OH} = −1 mA	2.4	3.3					
		I_{OH} = −2.6 mA				2.4	3.2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
		I_{OL} = 24 mA					0.35	0.5	
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			20			20	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.4 V			−20			−20	µA
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.4 V			−0.2			−0.2	mA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.25 V	−20		−112	−30		−112	mA
I_{CC}	V_{CC} = 5.5 V	Outputs high		10	18		10	18	mA
		Outputs low		15	24		15	24	
		Outputs disabled		16	30		16	30	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX§						UNIT
			SN54ALS576B		SN74ALS576B		SN74ALS577A		
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			22		30		30		MHz
t_{PLH}	CLK	Any $\overline{Q}$	4	24	3	14	4	14	ns
t_{PHL}			4	20	4	14	4	14	
t_{PZH}	$\overline{OE}$	Any $\overline{Q}$	4	24	3	18	4	18	ns
t_{PZL}			3	23	4	18	4	18	
t_{PHZ}	$\overline{OE}$	Any $\overline{Q}$	2	14	1	10	2	10	ns
t_{PLZ}			3	29	2	15	3	15	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 7 V
Voltage applied to a disabled 3-state output . . . . . 5.5 V
Operating free-air temperature range, T_A: SN54AS576 . . . . . −55°C to 125°C
SN74AS576 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54AS576			SN74AS576			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
I_{OH}	High-level output current				−12			−15	mA
I_{OL}	Low-level output current				32			48	mA
f_{clock}*	Clock frequency		0		100	0		125	MHz
t_w*	Pulse duration	CLK high	5			4			ns
		CLK low	4			2			
t_{su}*	Setup time, data before CLK↑		3			2			ns
t_h*	Hold time, data after CLK↑		3			2			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54AS576			SN74AS576			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}		V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −2 mA	V_{CC} −2			V_{CC} −2			V
		V_{CC} = 4.5 V	I_{OH} = −12 mA	2.4	3.2					
			I_{OH} = −15 mA				2.4	3.3		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 32 mA		0.29	0.5				V
			I_{OL} = 48 mA					0.33	0.5	
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			50			50	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.4 V			−50			−50	µA
I_I		V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}		V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	D	V_{CC} = 5.5 V,	V_I = 0.4 V			−3			−2	mA
	All others					−0.5			−0.5	
I_O‡		V_{CC} = 5.5 V,	V_O = 2.25 V	−30		−112	−30		−112	mA
I_{CC}		V_{CC} = 5.5 V	Outputs high		77	125		77	125	mA
			Outputs low		84	135		84	135	
			Outputs disabled		84	135		84	135	

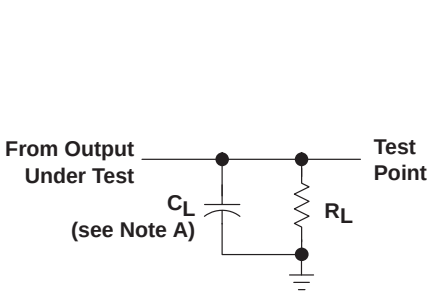
† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

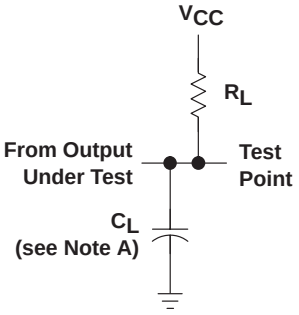
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX§				UNIT
			SN54AS576		SN74AS576		
			MIN	MAX	MIN	MAX	
f_{max}*			100		125		MHz
t_{PLH}	CLK	Any $\overline{Q}$	3	11	3	8	ns
t_{PHL}			4	11	4	9	
t_{PZH}	$\overline{OE}$	Any $\overline{Q}$	2	7	2	6	ns
t_{PZL}			3	11	3	10	
t_{PHZ}	$\overline{OE}$	Any $\overline{Q}$	2	7	2	6	ns
t_{PLZ}			2	7	2	6	

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.
§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

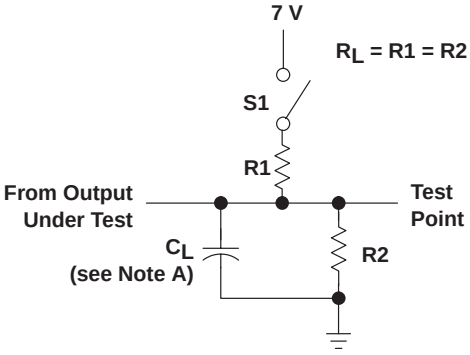
PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



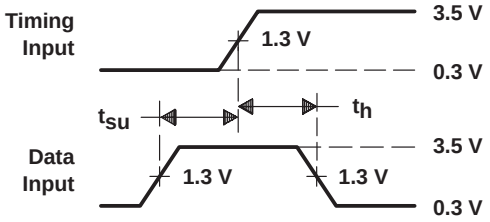
LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



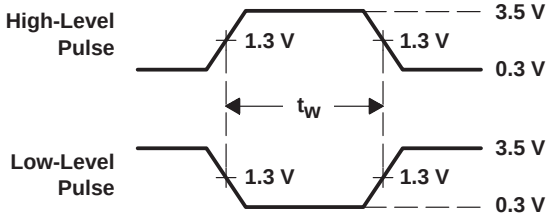
LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



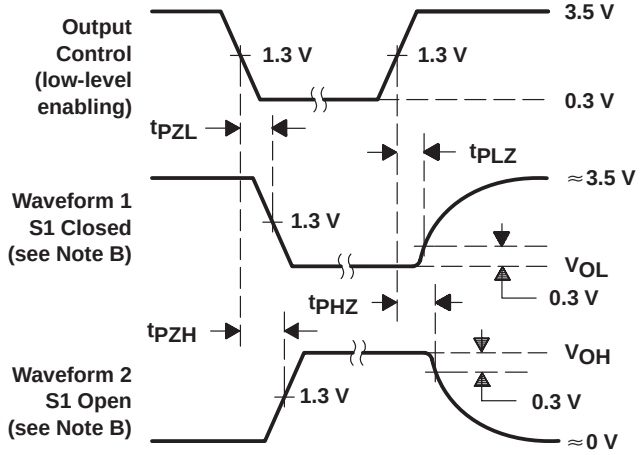
LOAD CIRCUIT
FOR 3-STATE OUTPUTS



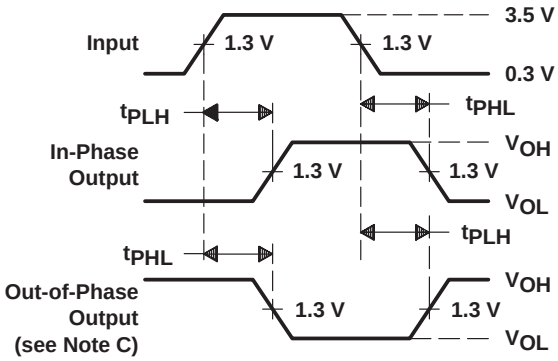
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
84001022A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8400102RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
8400102SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	
SN54ALS576BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74ALS576BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS576BN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	
SN74ALS576BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS576BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS576BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
SN74ALS577ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS577ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS577ANT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	
SN74ALS577ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS576DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS576DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS576DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS576N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS576NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54ALS576BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS576BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS576BW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
SNJ54AS576FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS576J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF SN54ALS576B, SN54AS576, SN74ALS576B, SN74AS576 :

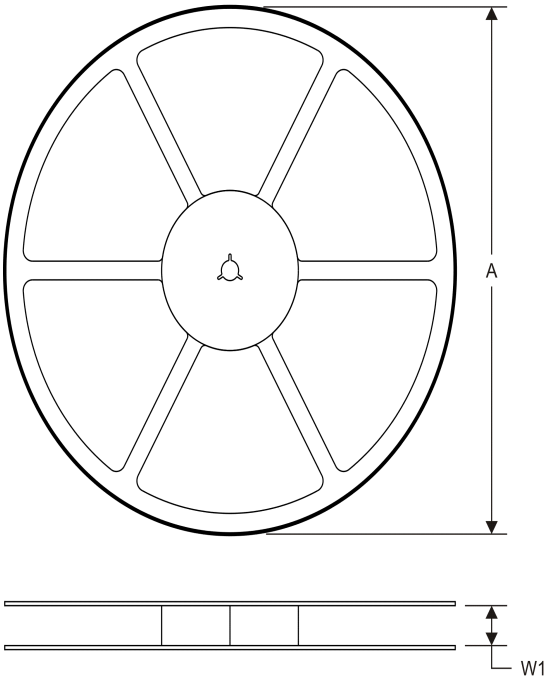
- Catalog: SN74ALS576B, SN74AS576
- Military: SN54ALS576B, SN54AS576

NOTE: Qualified Version Definitions:

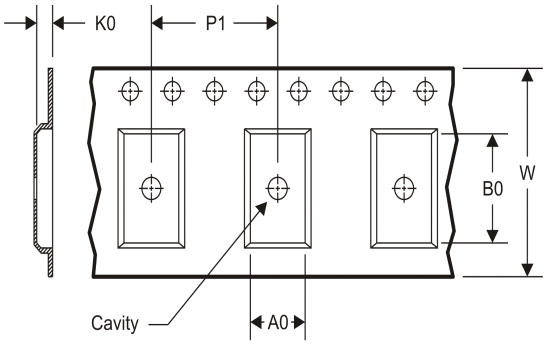
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



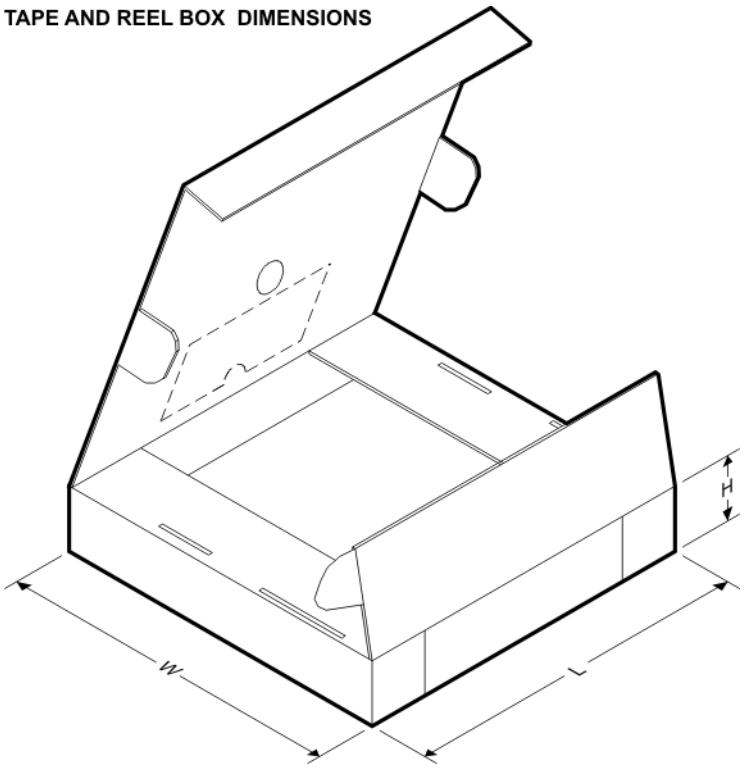
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS576BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS576BNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS577ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



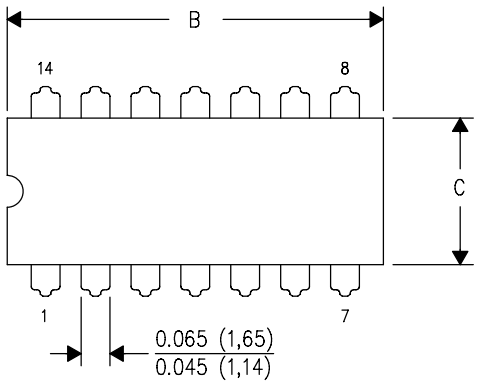
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS576BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS576BNSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS577ADWR	SOIC	DW	24	2000	367.0	367.0	45.0

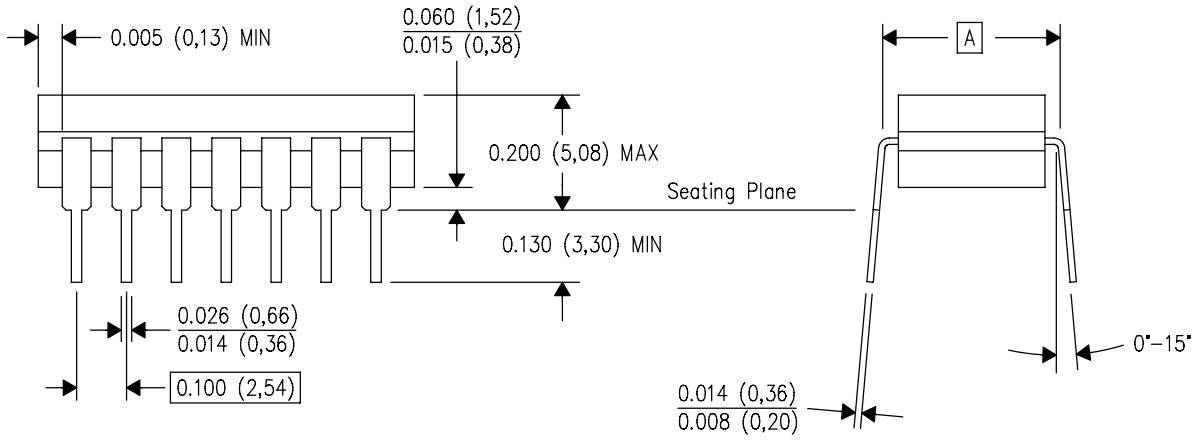
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



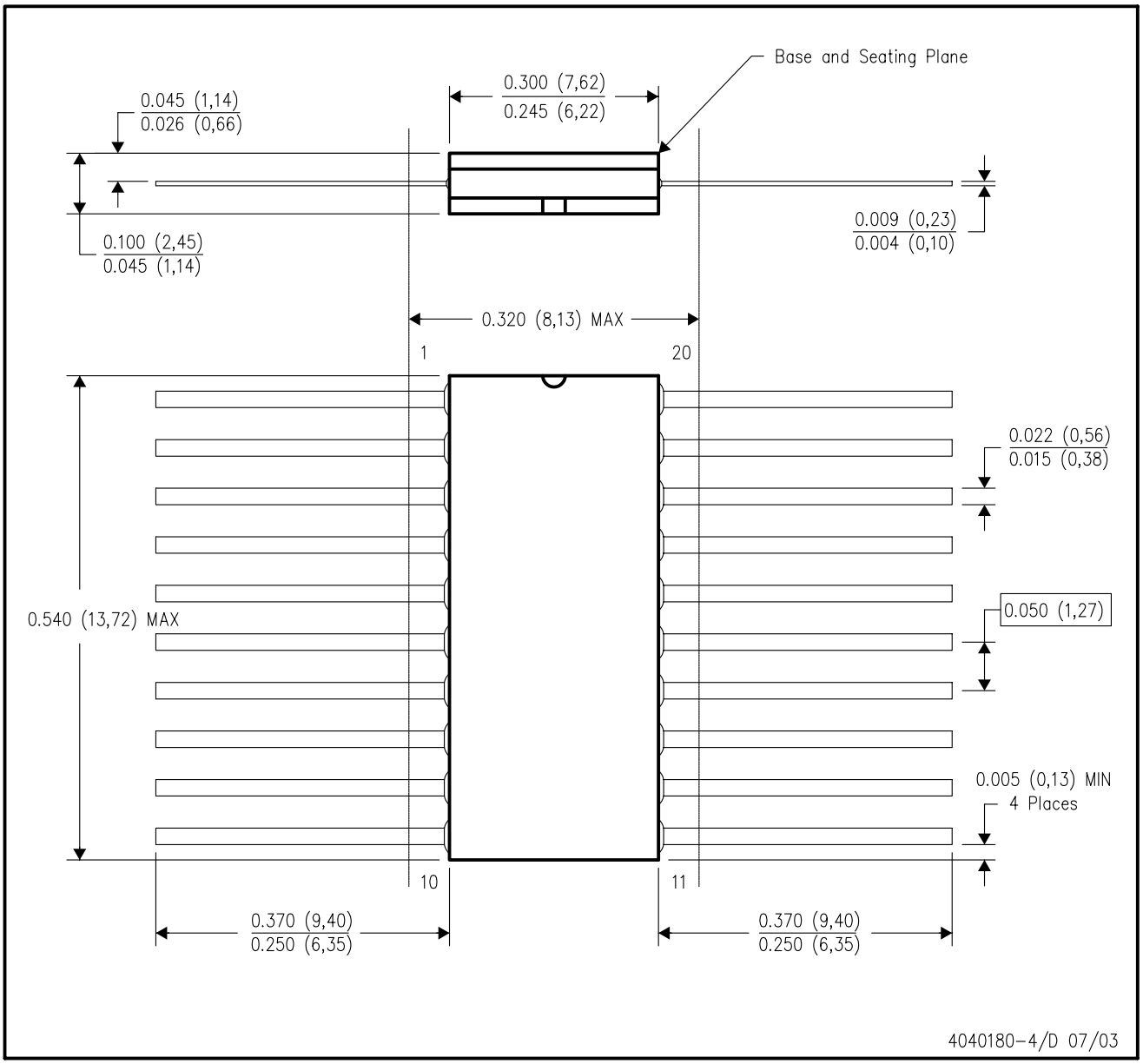
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

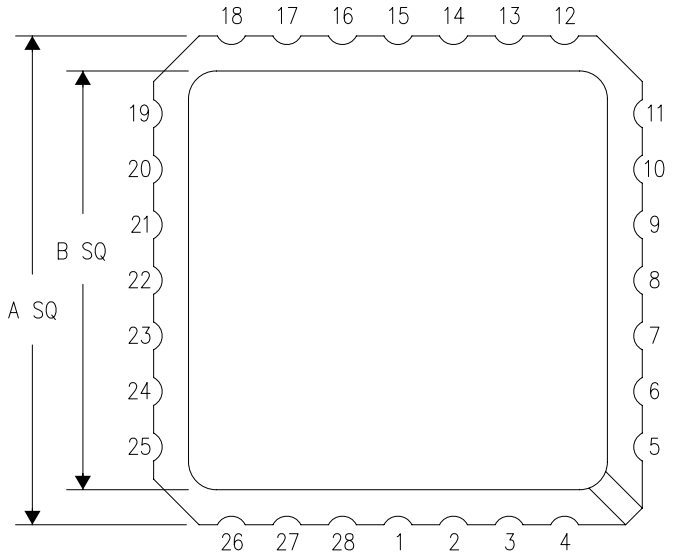
W (R–GDFP–F20) CERAMIC DUAL FLATPACK



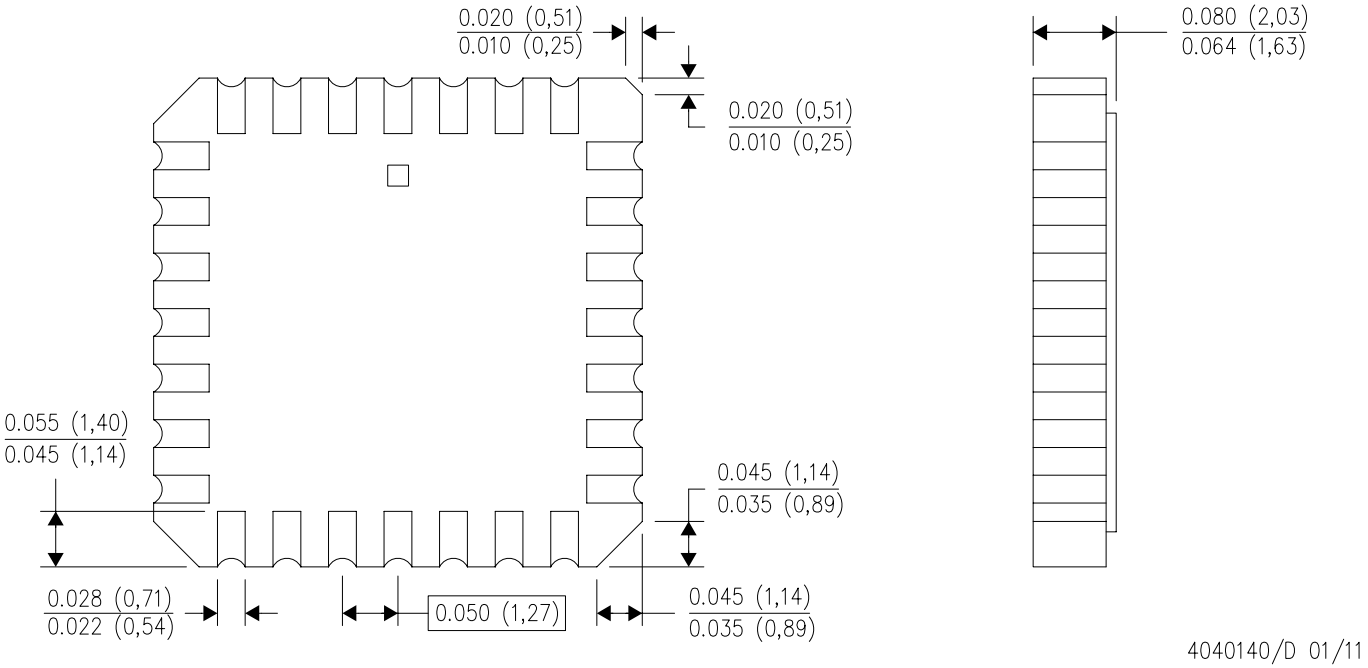
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



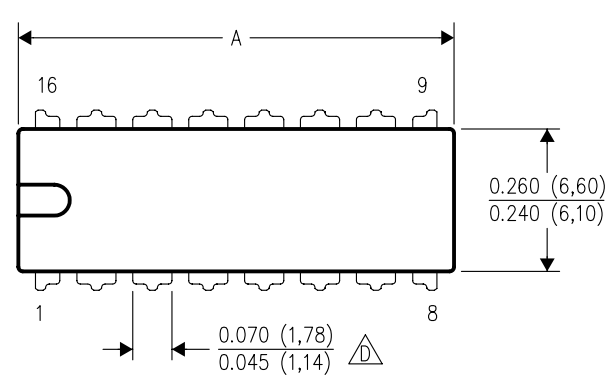
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

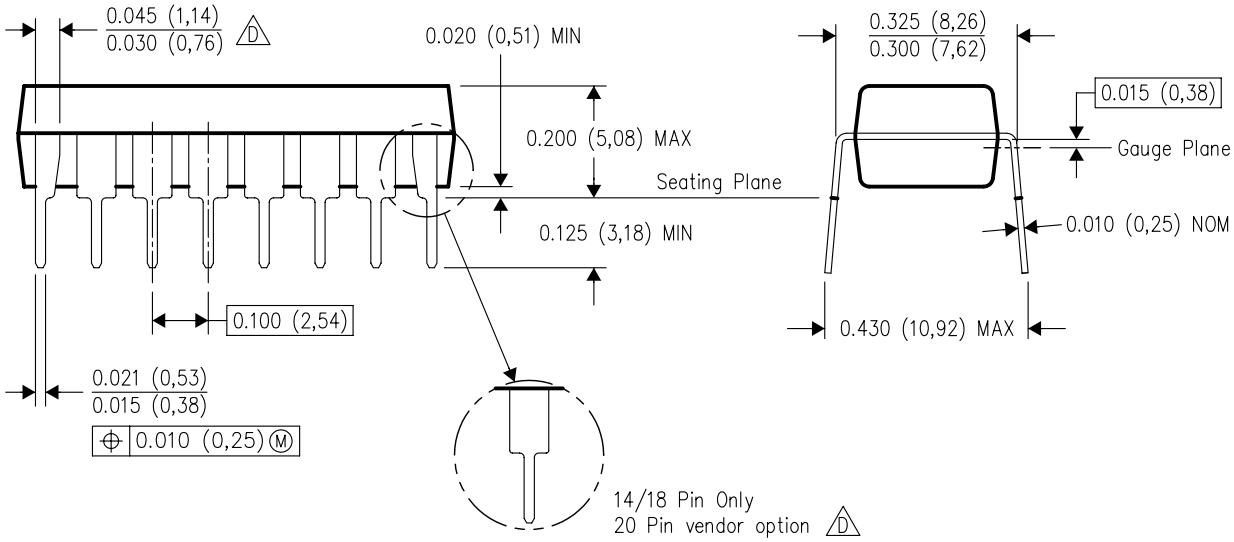
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD

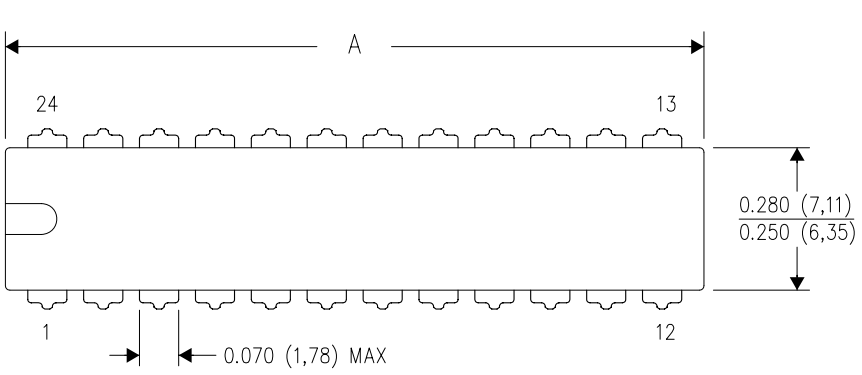


4040049/E 12/2002

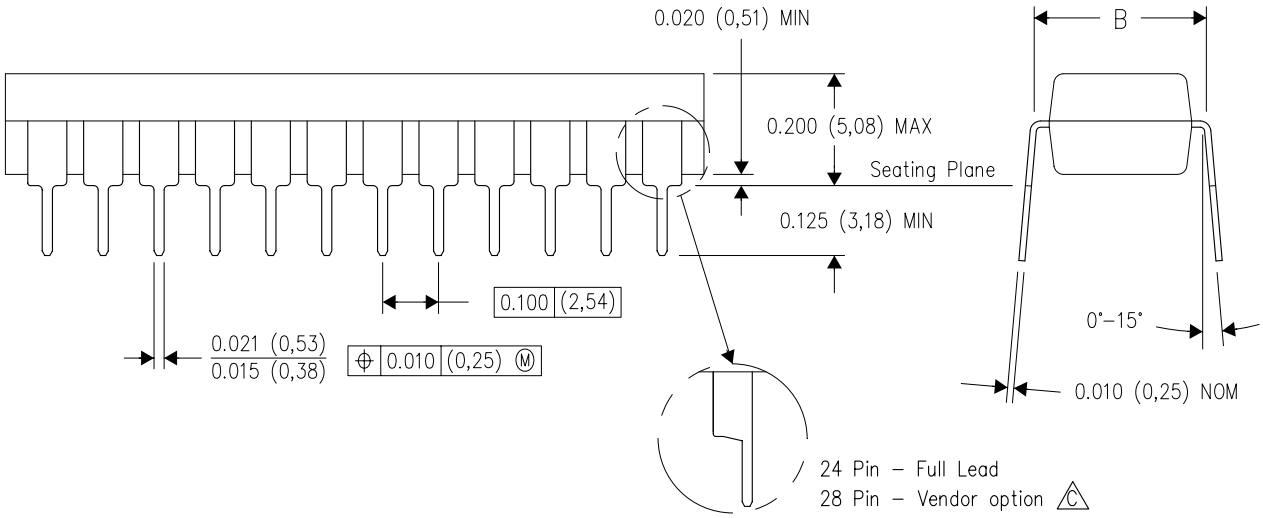
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

NT (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

24 PINS SHOWN



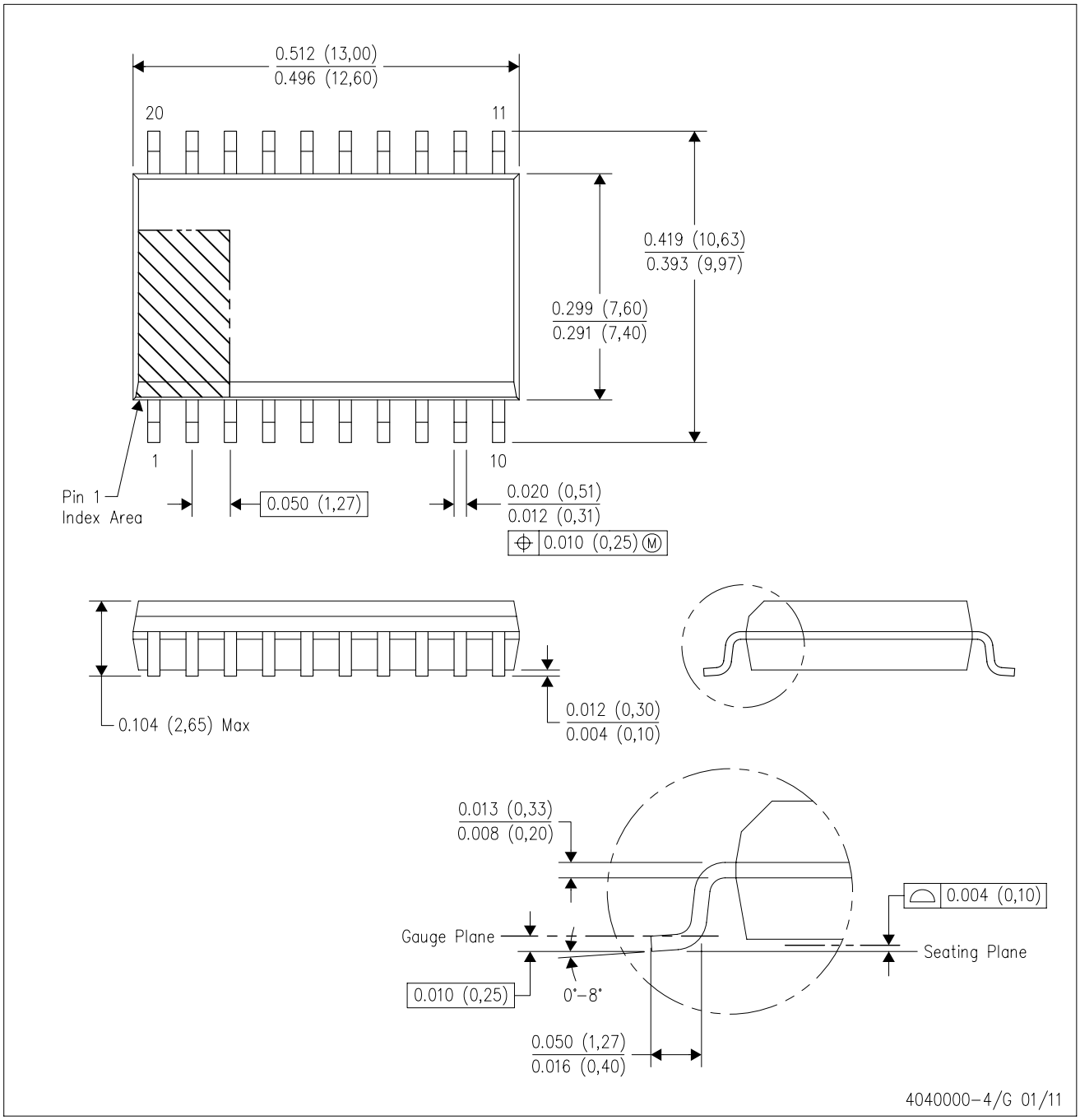
DIM \ PINS **	24	28
A MAX	1.260 (32,04)	1.425 (36,20)
A MIN	1.230 (31,24)	1.385 (35,18)
B MAX	0.310 (7,87)	0.315 (8,00)
B MIN	0.290 (7,37)	0.295 (7,49)



4040050/C 04/09

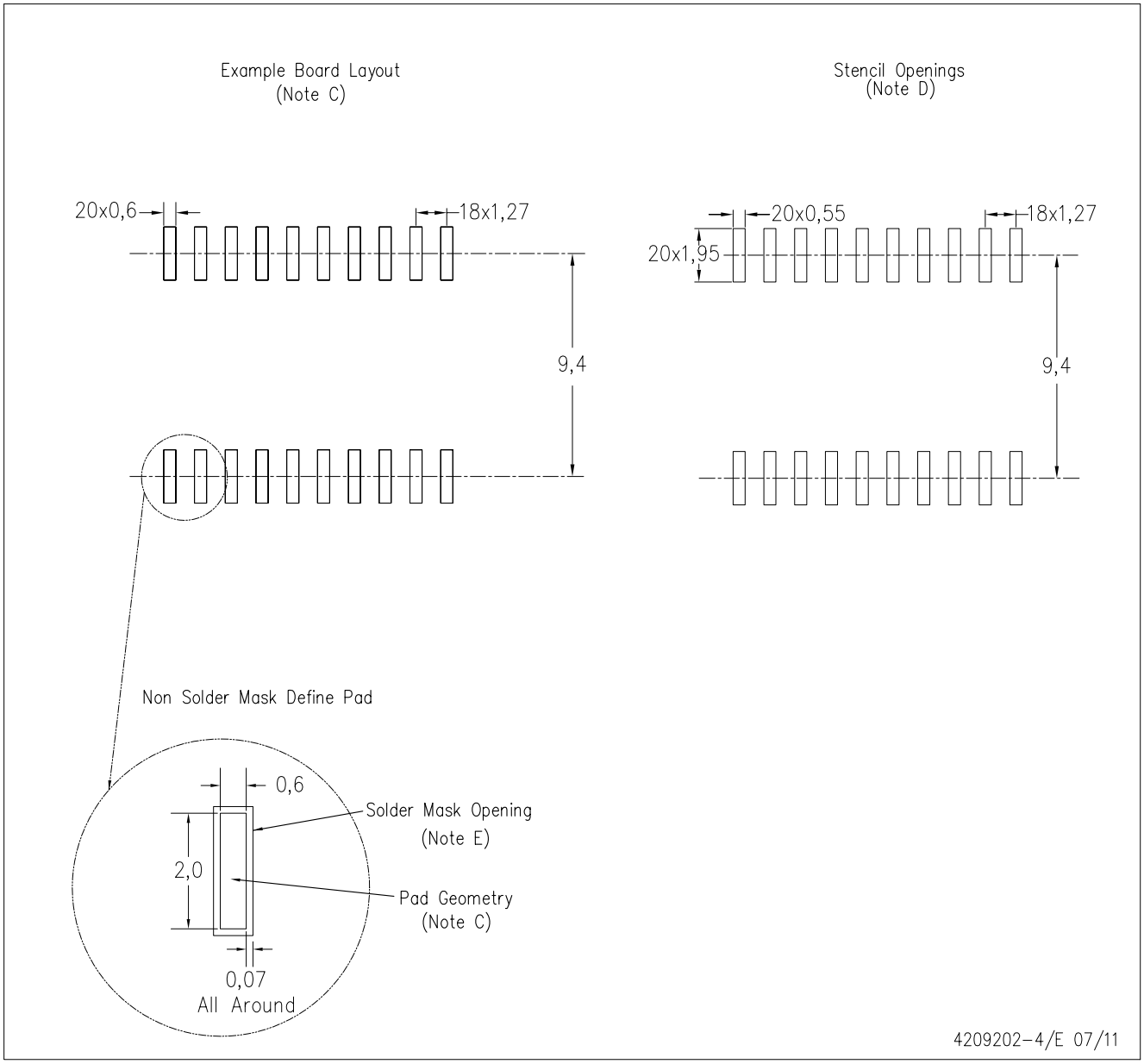
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



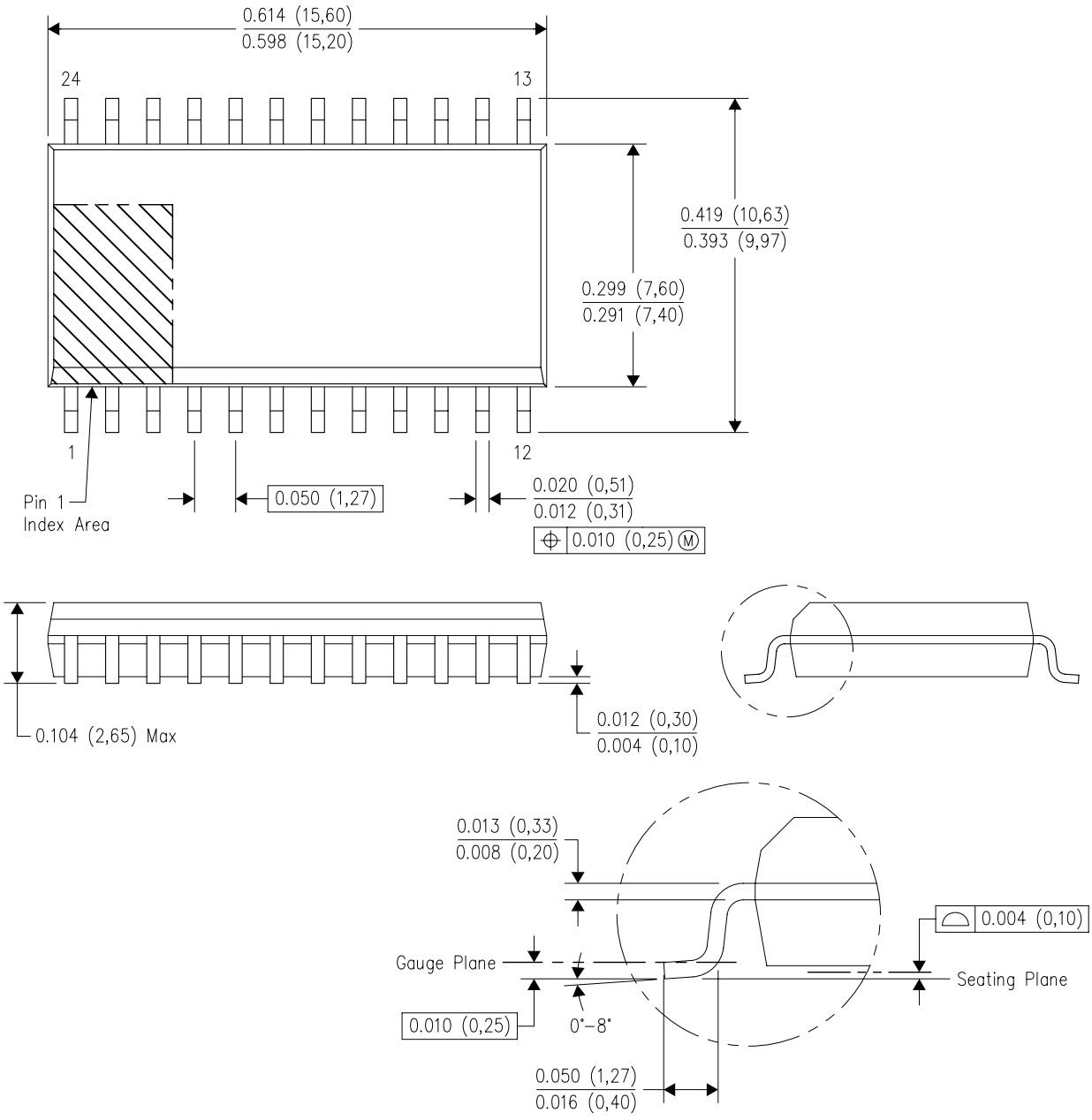
NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE

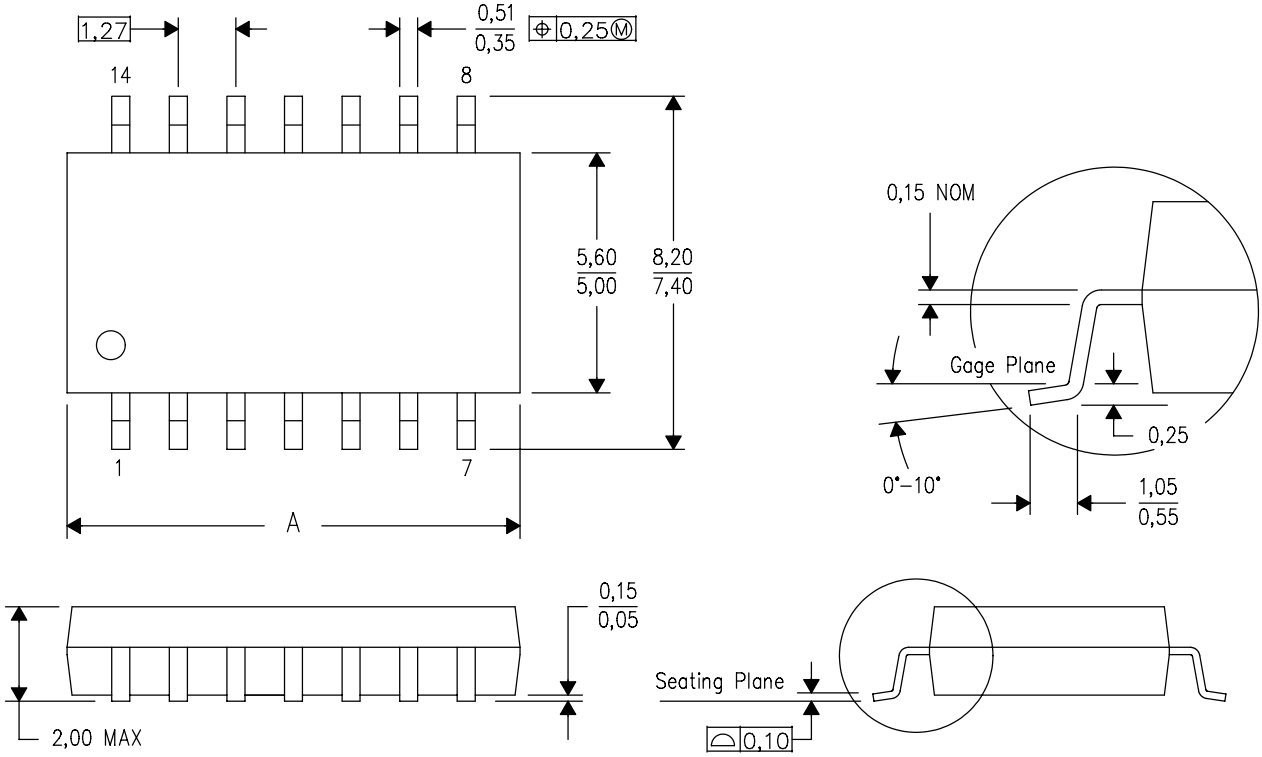


NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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